

091-893316

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I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the U.S. Postal Service on the date shown below with sufficient postage as First Class Mail, in an envelope addressed to: Attention: Certificate of Correction Branch, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Dated: 01/19/2007 Signature: Melody Almberg
(Melody Almberg)

Docket No.: 291958161US1
Client Ref No. 01-0046US2

(PATENT)



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Letters Patent of:
Reardon et al.

Patent No.: 7,094,291

Issued: August 22, 2006

For: SEMICONDUCTOR PROCESSING SPRAY
COATING APPARATUS

*Certificate
JAN 24 2007
of Correction*

REQUEST FOR CERTIFICATE OF CORRECTION PURSUANT TO 37 CFR 1.322

Attention: Certificate of Correction Branch
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Upon reviewing the above-identified patent, Patentee noted a typographical error which should be corrected.

In the Specification:

Front page, cited references: Please include the cited references from the resubmission of an Information Disclosure Statement filed June 17, 2005. The original Information Disclosure Statement was filed December 31, 2001 but did not include copies of references.

The error was not in the application as filed by applicant; accordingly no fee is required.

Transmitted herewith is a proposed Certificate of Correction effecting such amendment. Patentee respectfully solicits the granting of the requested Certificate of Correction.

Applicant believes no fee is due with this request. However, if a fee is due, please charge our Deposit Account No. 50-0665, under Order No. 291958161US1 from which the undersigned is authorized to draw.

Dated: January 19, 2006

Respectfully submitted,

By P.T. Parker
Paul T. Parker

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Attorney for Applicant

UNITED STATES PATENT AND TRADEMARK OFFICE
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Page 1 of 3

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US-5,358,740	10-25-1994	Bornside et al.	US-5,378,511	01-03-1995	Cardinali et al.

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US-4,457,259	07-03-1984	Samuels	US-4,457,419	07-03-1984	Ogami et al.
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JP-45-40458	12/1970		JP-1-204427	08-17-1989	Hitachi Ltd.
JP-1-304732	11-17-1998	Kubota Corp.	JP-231330	11-16-1985	Seiichiou Sougou
JP-54-161275	12-20-1979	Toshiba Corp.	JP-56-88320	07-17-1981	Fujitsu Ltd.
JP-58-19475	02-04-1983	Asahi Chem Ind Co. Ltd	JP-59-166675	09-20-1984	Fujitsu KK
JP-61-148820	07-07-1986	Hitachi Ltd.			
JP-54-71991	06-08-1979	Matsushita Electronics Corp.			
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